

AMENDMENTS TO THE CLAIMS:

1.(currently amended): A communication device that generates heat, comprising:

a high-temperature heat-generating section that generates high-temperature heat;

a first heat-dissipating fin section mounted on said high-temperature heat-generating section, said first heat-dissipating fin section having a heat pipe and fins provided on said heat pipe;

a low-temperature heat-generating section that generates low-temperature heat having a lower temperature than that of the high-temperature heat generated by said high-temperature heat-generating section; [[and]]

a second heat-dissipating fin section mounted on said low-temperature heat-generating section, said second heat-dissipating fin section having a heat-receiving plate, and fins provided on said heat-receiving plate; and

a protection cover for covering said first heat-dissipating fin section, wherein

said fins provided on said heat pipe are fixed to said protection cover,

said first heat-dissipating fin section has a heat-receiving plate having said heat pipe disposed thereon, and

said protection cover is fixed to said heat-receiving plate having said heat pipe disposed thereon, via a heat-resistant resin having a low thermal conductivity.

Claims 2-3. (canceled):

4.(currently amended): The communication device as claimed in claim [[2]] 1, wherein an inside of said protection cover and said fins of said first heat-dissipating fin section are rigidly fixed to each other by brazing.

5.(original): The communication device as claimed in claim 1, wherein said first heat-dissipating fin section has a heat-receiving plate having said heat pipe disposed thereon,
wherein said high-temperature heat-generating section includes a printed board,
and
wherein said printed board is rigidly fixed to said heat-receiving plate having said heat pipe disposed thereon.

6.(original): The communication device as claimed in claim 1, wherein said first heat-dissipating fin section has a heat-receiving plate having said heat pipe disposed thereon,
wherein said high-temperature heat-generating section includes components that generate heat, and
wherein said components are in contact with said heat-receiving plate having said heat pipe disposed thereon.

7.(original): The communication device as claimed in claim 6, wherein said components are transistors.

8.(original): ~~[[The]]~~ A communication device that generates heat, comprising: as claimed in claim 1;

a high-temperature heat-generating section that generates high-temperature heat;
a first heat-dissipating fin section mounted on said high-temperature heat-generating section, said first heat-dissipating fin section having a heat pipe and fins provided on said heat pipe;

a low-temperature heat-generating section that generates low-temperature heat having a lower temperature than that of the high-temperature heat generated by said high-temperature heat-generating section;

a second heat-dissipating fin section mounted on said low-temperature heat-generating section, said second heat-dissipating fin section having a heat-receiving plate, and fins provided on said heat-receiving plate; and

including an air duct cover for covering said fins of said first heat-dissipating fin section and said fins of said second heat-dissipating fin section to cause air from a cooling fan to pass between said fins of said first heat-dissipating fin section and said fins of said second heat-dissipating fin section.